INSTRUMENTS Data sheet acquired from Harris Semiconductor SCHS024C – Revised October 2003

CMOS 8-Stage Static Shift Registers

High-Voltage Types (20-Volt Rating) CD4014B:

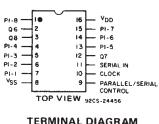
Synchronous Parallel or Serial Input/Serial Output

CD4021B:

Asynchronous Parallel Input or Synchronous Serial Input/Serial Output

CD4014B and CD4021B series types are 8-stage parallel- or serial-input/serial output registers having common CLOCK and PARALLEL/SERIAL CONTROL inputs, a single SERIAL data input, and individual parallel "JAM" inputs to each register stage. Each register stage is a D-type, master-slave flip-flop. In addition to an output from stage 8, "Q" outputs are also available from stages 6 and 7. Parallel as well as serial entry is made into the register synchronously with the positive clock line transition in the CD4014B. In the CD4021B serial entry is synchronous with the clock but parallel entry is asynchronous. In both types, entry is controlled by the PARALLEL/SERIAL CONTROL input. When the PARALLEL/SERIAL CON-TROL input is low, data is serially shifted into the 8-stage register synchronously with the positive transition of the clock line. When the PARALLEL/SERIAL CONTROL input is high, data is jammed into the 8-stage register via the parallel input lines and synchronous with the positive transition of the clock line. In the CD4021B, the CLOCK input of the internal stage is "forced" when asynchronous parallel entry is made. Register expansion using multiple packages is permitted.

The CD4014B and CD4021b series types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).



CD4014B, CD4021B

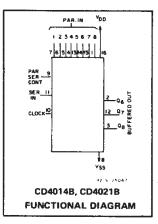
CD4014B, CD4021B Types

Features:

- Medium-speed operation . . . 12 MHz (typ.) clock rate at VDD-VSS = 10 V
- Fully static operation
- 8 master-slave flip-flops plus output buffering and control gating
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μA at 18 V over full package-temperature range; 100 nA at 18 V and 25^oC
- Noise margin (full package-temperature range) = 1 V at VDD = 5 V 2 V at VDD = 10 V

2.5 V at V_{DD} = 15 V

- Standardized, symmetrical output characteristics
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"



Applications:

- Parallel input/serial output data queueing
- Parallel to serial data conversion
- General-purpose register

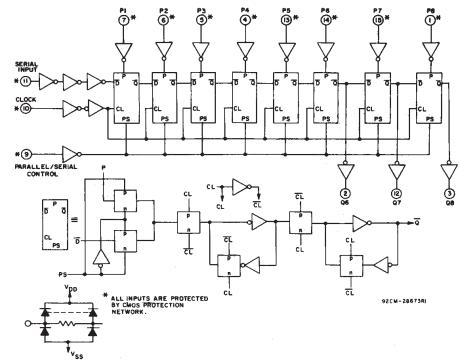
RECOMMENDED OPERATING CONDITIONS AT $T_A = 25^{\circ}$ C, Unless Otherwise Specified For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges.

CHARACTERISTIC	Vaa	LIN			
	V _{DD} (V)	Min.	Max.		
Supply-Voltage Range (T _A = Full Package-Temperature Range)		3	18	v	
Clock Pulse Width, t _W	5 10 15	180 80 50	-	ns	
Clock Frequency, f _{CL}	5 10 15		3 6 8.5	MHz	
Clock Rise and Fall Time, t _r CL, t _f CL	5 10 15		15 15 15	μs	
Set-up Time, t _s : Serial Input (ref. to CL)	5 10 15	120 80 60	_ _ _	ns	
Parallel Inputs CD4014B (ref. to CL)	5 10 15	80 50 40		ns	
Parallel Inputs CD4021B (ref. to P/S)	5 10 15	50 30 20	_ _ _	ns	
Parallel/Serial Control CD4014B (ref. to CL)	5 10 15	180 80 60	-	ns	
Parallel/Serial Pulse Width, t _W (CD4021B)	5 10 15	160 80 50	 	ns	
Parallel/Serial Removal Time, tREM (CD4021B)	5 10 15	280 140 100	_ _ _	ns	

Copyright © 2003, Texas Instruments Incorporated

CD4014B, CD4021B Types

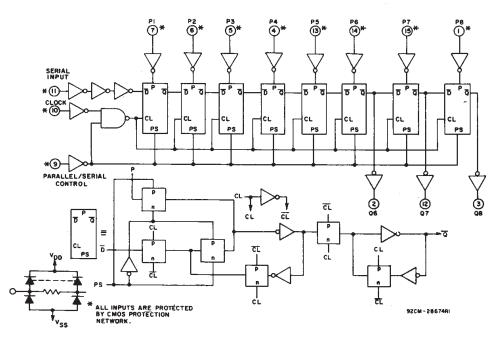
÷.,



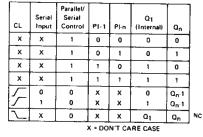
2



Fig. 1 - Logic diagram for CD4014B.



TRUTH TABLE - CD4021B





CD4014B, CD4021B Types

LIMITS AT INDICATED TEMPERATURES (°C)

+125

150

300

600

3000

0.36

0.9

2.4

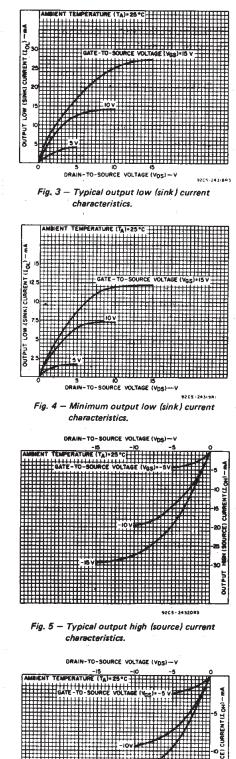
-0.36

-1.15

-0.9

-2.4

MAXIMUM RATINGS, Absolute-Maximum Values:	
DC SUPPLY-VOLTAGE RANGE, (VDD)	
Voltages referenced to VSS Terminal)	
INPUT VOLTAGE RANGE, ALL INPUTS	
DC INPUT CURRENT, ANY ONE INPUT	±10mA
POWER DISSIPATION PER PACKAGE (PD):	
For $T_A = -55^{\circ}C$ to $+100^{\circ}C$	
For TA = +100°C to +125°C Derate Linea	rity at 12mW/ ⁰ C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	
FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)	
OPERATING-TEMPERATURE RANGE (TA).	55°C to +125°C
STORAGE TEMPERATURE RANGE (Tato)	65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):	
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max	+265°C



U N

ŧ

T

S

ıΑ

Max.

5

10

20

100

_

- mA

_

_

_

0.05

_

1.5

3

4 v

_

_

_

±0.1 | µA

v

+25

Typ.

0.04

0.04

0.04

0.08

1 –

2.6 -

6.8

 $^{-1}$

-3.2

-2.6

-6.8

0 0.05

0

0 0.05

5 -

10 -

15

_

_

_

_

±10⁻⁵

Min.

_

<u>.</u>

0.51

1.3

3.4

0.51

-1.6

-1.3

-3.4

_

_

_

4.95

9.95

14.95

_

_

3.5

11

7

STATIC ELECTRICAL CHARACTERISTICS

vo

(V)

—

_

_

_

0.4

0.5

1.5

4.6

2.5

9.5

13.5

_

teri.

_

_

_

_

0.5,4.5

1,9

.5,13.5

0.5,4.5

1,9

1.5,13.5

CONDITIONS

V_{IN}

 (\mathbf{V})

0,5

0,10

0.15

0,20

0,5

0,10

0,15

0,5

0,5

0,10

0,15

0,5

0,10

0.15

0.5

0,10

0,15

_

__

_

_

_

_

0,18

VDD

(V)

5

10

15

20

5

10

15

5

5

10

15

5

10

15

5

10

15

5

10

15

5

10

15

18

±0.1

-55

5

10

20

100

0.64

1.6

4.2

0.64

-1.6

-4.2

-2

-40

5

10

20

100

0.61

-0.61

-1.8

-1.5

-4

0.05

0.05

0.05

4.95

9.95

14.95

1.5

3

4

7

11

±1

±1

±0.1

3.5

1.5

4

+85

150

300

600

3000

0.42

1.1

2.8

-0.42

-1.3

-1.1

-2.8

CHARAC-

TERISTIC

Quiescent

Current.

IDD Max.

Output Low

IOL Min.

Output High

(Source)

Current.

IOH Min.

Output Voltage Low-Level,

VOL Max.

Output

Voltage:

High-Level,

VOH Min.

Input Low

Voltage

VIL Max.

Input High Voltage,

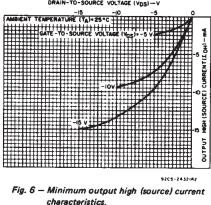
VIH Min.

Input Current

IIN Max.

(Sink) Current

Device



5.00	

3-39

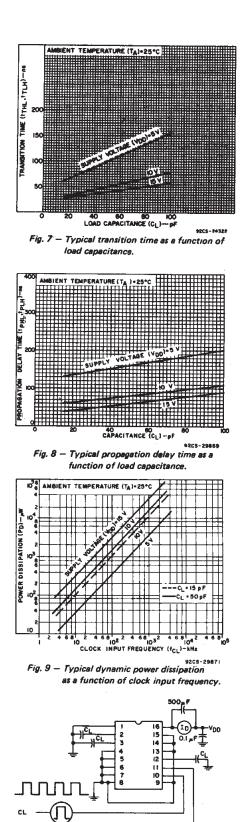
COMMERCIAL CMOS HIGH VOLTAGE ICS

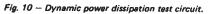
3

DYNAMIC ELECTRICAL CHARACTERISTICS at T_A=25°C, Input t_r,t_f=20 ns, CL=50 pF, R1=200 K Ω

	TEST CONDITIONS		LIMITS			
CHARACTERISTIC		V _{DD} (V)	Min.	Тур.	Max.	UNITS
Propagation Delay Time,	1.1.1	- 5	-	160	320	
tPLH, tPHL		10	-	80	160	ns
		15	-	60	120	
Transition Time,	1	5		100	200	
tTHL, tTLH		10	-	50	100	ns
		15		40	80	
Maximum Clock Input		5	3	6	-	
Frequency, f _{CL}		10	6	12	_	MHz
		15	8.5	17	_	
Minimum Clock Pulse		5	-	90	180	
Width, tw		10	-	40	80	ns
		15		25	50	
Clock Rise and Fall Time,		5	_	-	15	
t _r CL, t _f CL*		10	-	-	15	μs
		15		-	15	
Minimum Set-up Time, t _s :		5		60	120	
Serial Input		10	-	40	80	ns
(ref. to CL)		15	-	30	60	
Parallel Inputs		5		40	80	
CD4014B		10	- 1	25	50	ns
(ref. to CL)		15		20	40	
Parallel Inputs		5		25	50	
CD4021 B	1 1	10	-	15	30	ns
(ref. to P/S)		15	-	10	20	
Parallel/Serial Control		5	_	90	180	
CD4014B		10		40	80	ns
(ref. to CL)		15	-	30	60	
Minimum Hold Time, tH:		5	-		0	
Serial In, Parallel In,		10	_	- 1	0	ns
Parallel/Serial Control		15	-	-	0	
Minimum P/S Pulse Width,		5		80	160	
tWH		10		40	80	ns
(CD4021B)		15	-	25	50	
Minimum P/S Removal Time,		5		140	280	
^t REM		10	_	70	140	ns
CD4021B (ref. to CL)		15	·	50	100	113
Average Input Capacitance, C	Anv	Input	_	5	7.5	ρF
				Ŭ	,	м

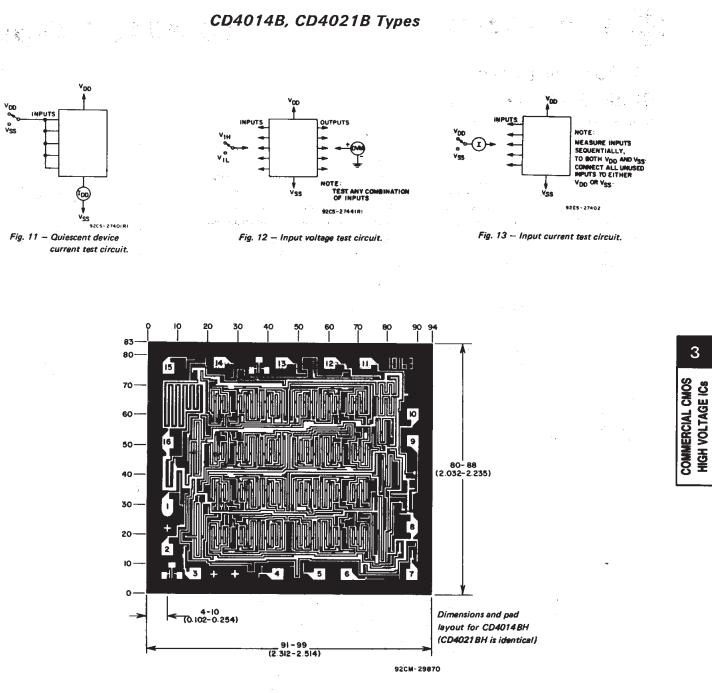
* If more than one unit is cascaded t_pCL should be made less than or equal to the sum of the transition time and the fixed propagation delay of the output of the driving stage for the estimated capacitive load.





92CS-29871

SER- DATA (1/4 fcL)



Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch) .

. .

3

TEXAS

28-Feb-2005

PACKAGING INFORMATION

Orderable Devi	ce Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
CD4014BE	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4014BF3A	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4014BM	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4014BM96	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4014BMT	ACTIVE	SOIC	D	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4014BNSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4014BPW	ACTIVE	TSSOP	PW	16	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4014BPWF	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4021BE	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4021BF	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4021BF3A	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4021BM	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4021BM96	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4021BMT	ACTIVE	SOIC	D	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4021BNSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4021BPW	ACTIVE	TSSOP	PW	16	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4021BPWF	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
JM38510/05754E	EA ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.



Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



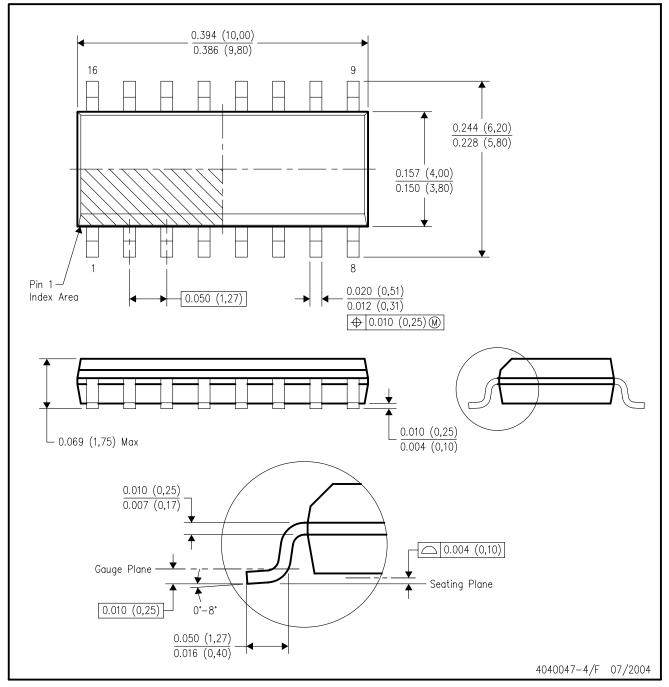
NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AC.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address:

Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated

Copyright © Each Manufacturing Company.

All Datasheets cannot be modified without permission.

This datasheet has been download from :

www.AllDataSheet.com

100% Free DataSheet Search Site.

Free Download.

No Register.

Fast Search System.

www.AllDataSheet.com